

TDA1904

4W AUDIO AMPLIFIER

- HIGH OUTPUT CURRENT CAPABILITY
- PROTECTION AGAINST CHIP OVERTEM-PERATURE
- LOW NOISE
- HIGH SUPPLY VOLTAGE REJECTION
- SUPPLY VOLTAGE RANGE: 4V TO 20V

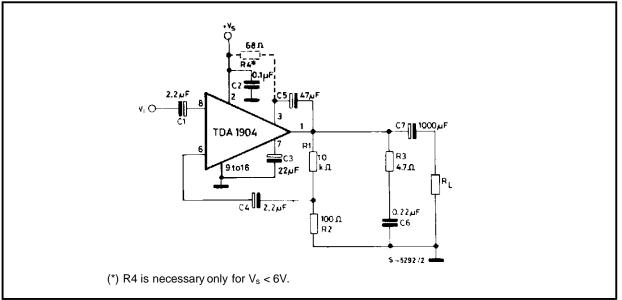
DESCRIPTION

The TDA 1904 is a monolithic integrated circuit in POWERDIP package intended for use as low-frequency power amplifier in wide range of applications in portable radio and TV sets.

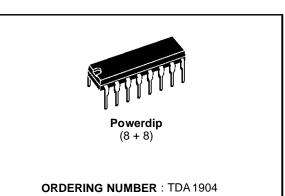


Symbol	Parameter	Value	Unit
Vs	Supply voltage	20	V
Ι _Ο	Peak output current (non repetitive)	2.5	А
lo	Peak output current (repetitive)	2	А
P _{tot}	Total power dissipation at $T_{amb} = 80^{\circ}C$	1	W
	at T _{pins} = 60°C	6	W
T _{stg} , T _j	Storage and junction temperature	-40 to 150	°C

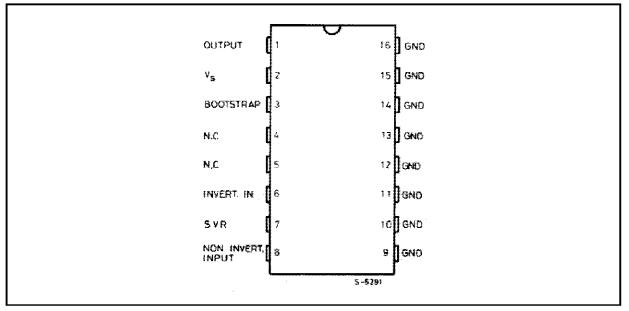
TEST AND APPLICATION CIRCUIT



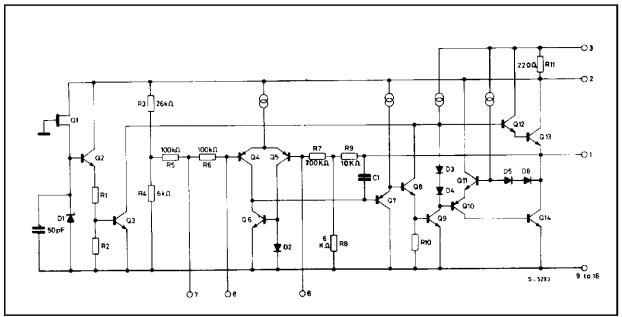
March 1993



PIN CONNECTION (top view)



SCHEMATIC DIAGRAM



THERMAL DATA

Symbol	Parameter	Value	Unit
R _{th-j-case}	Thermal resistance junction-pins max	15	°C/W
R _{th-j-amb}	Thermal resistance junction-ambient max	70	°C/W



ELECTRICAL CHARACTERISTICS (Refer to the test circuit, $T_{amb} = 25$	°C, R _{th}	(heatsinl	<) =
20 °C/W, unless otherwisw specified)				

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Vs	Supply voltage		4		20	V
Vo	Quiescent output voltage	$V_s = 4V$ $V_s = 14V$		2.1 7.2		V
l _d	Quiescent drain current	$V_s = 9V$ $V_s = 14V$		8 10	15 18	mA
Po	Output power		1.8 4 3.1 0.7	2 4.5		w
d	Harmonic distortion			0.1	0.3	%
Vi	Input saturation voltage (rms)	V _s = 9V V _s = 14V	0.8 1.3			V
Ri	Input resistance (pin 8)	f = 1 KHz	55	150		KΩ
η	Efficiency	$ \begin{array}{l} f=1 \ \text{KHz} \\ \text{V}_{\text{S}}=9 \text{V} \\ \text{V}_{\text{S}}=14 \text{V} \\ \text{R}_{\text{L}}=4 \Omega \\ \text{P}_{\text{O}}=2 \text{W} \\ \text{P}_{\text{O}}=4.5 \text{W} \end{array} $		70 65		%
BW	Small signal bandwidth (-3 dB)	$V_s = 14V$ $R_L = 4\Omega$	40 to 40,000		00	Hz
Gv	Voltage gain (open loop)	V _s = 14V f = 1 KHz		75		dB
Gv	Voltage gain (closed loop)		39.5	40	40.5	dB
e _N	Total input noise	$ \begin{array}{l} R_{g} = 50\Omega \\ R_{g} = 10 \;K\Omega \end{array} \tag{$^\circ$} $		1.2 2	4	μV
		$ \begin{array}{l} R_{g} = 50\Omega \\ R_{g} = 10 \;K\Omega \end{array} \tag{$^\circ\circ$} $		2 3		μV
SVR	Supply voltage rejection	$ \begin{array}{l} V_s = 12 V \\ f_{ripple} = 100 \mbox{ Hz} \\ V_{ripple} = 0.5 \mbox{ Vrms} \end{array} R_g = 10 \mbox{ K}\Omega \label{eq:ripple}$	40	50		dB
T _{sd}	Thermal shut-down case temperature	P _{tot} = 2W		120		ÉC

Note: (°) Weighting filter = curve A.

(°°) Filter with noise bendwidth: 22Hz to 22 KHz.





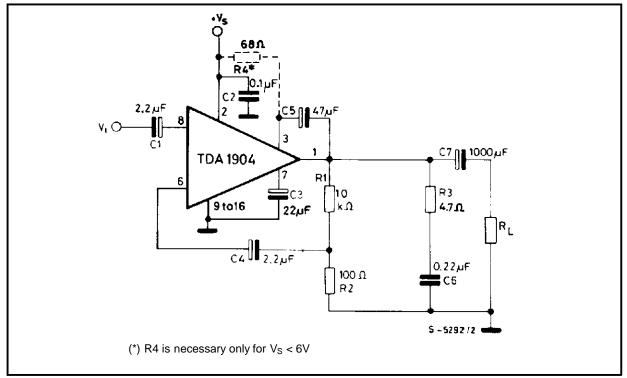
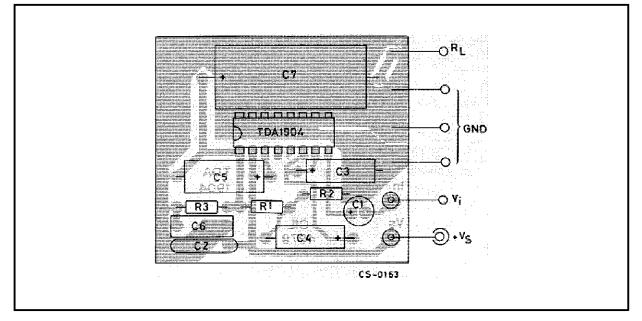


Figure 2. P.C. board and components layout of fig. 1 (1 : 1 scale)



APPLICATION SUGGESTION

The recommended values of the external components are those shown on the application circuit of fig. 1.

When the supply voltage V_S is less than 6V, a 68Ω resistor must be connected between pin 2 and pin

3 in order to obtain the maximum output power. Different values can be used. The following table can help the designer.

Components	Recomm.	Purpose	Larger than	Smaller than	Allowed range	
components	value	Fulbose	recommended value	recommended value	Min.	Max.
R1	10 KΩ	Feedback resistors	Increase of gain.	Decrease of gain. Increase quiescent current.	9R3	
R2	100 Ω		Decrease of gain.	Increase of gain.		1 KΩ
R3	4.7 Ω	Frequency stability	Danger of oscillation at high frequencies with inductive loads.			
R4	68 Ω	Increase of the output swing with low supply voltage.			39 Ω	220 Ω
C1	2.2 μF	Input DC decoupling.	Higher cost lower noise.	Higher low frequency cutoff. Higher noise.		
C2	0.1 μF	Supply voltage bypass.		Danger of oscillations.		
C3	22 μF	Ripple rejection	Increase of SVR increase of the switch-on time.	Degradation of SVR.	2.2 μF	100ΩF
C4	2.2 μF	Inverting input DC decoupling.	Increase of the switch-on noise	Higher low frequency cutoff.	0.1 ΩF	
C5	47 μF	Bootstrap.		Increase of the distortion at low frequency.	10 μF	100µF
C6	0.22 μF	Frequency stability.		Danger of oscillation.		
C7	1000 μF	Output DC decoupling		Higher low frequency cutoff.		



Figure 3. Quiescent output voltage vs. supply voltage

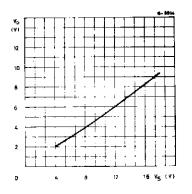


Figure 4. Quiescent drain current vs. supply voltage

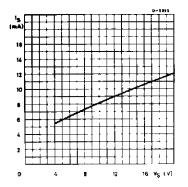


Figure 5. Output power vs. supply voltage

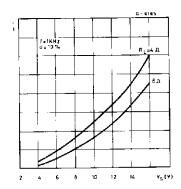


Figure 6. Distortion vs. output power

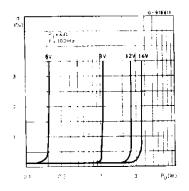


Figure 7. Distortion vs. output power

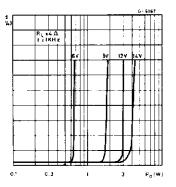


Figure 8. Distortion vs. output power

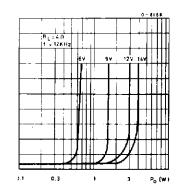


Figure 9. Distortion vs. output power

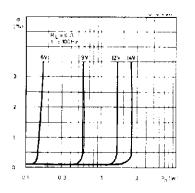
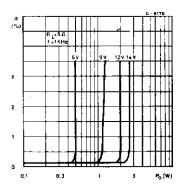


Figure 10. Distortion vs. output power



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16 11 10

Figure 11. Distortion vs. output power

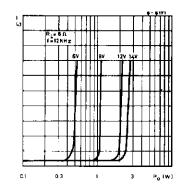


Figure 12. Distortion vs. frequency

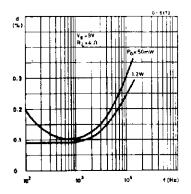


Figure 13. Distortion vs. frequency

ه ۱۳۵۵ Vs=14V Rt=40

04

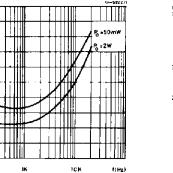
0.3

0.1

0

100

Figure 14. Distortion vs. frequency



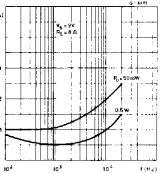


Figure 15. Distortion vs. frequency

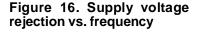
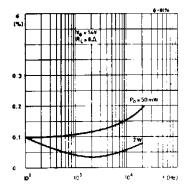
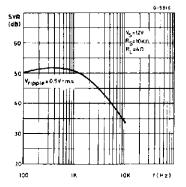


Figure 17. Total power dissipation and efficiency vs. output power





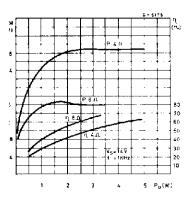


Figure 18. Total power dissipation and efficiency vs. output power

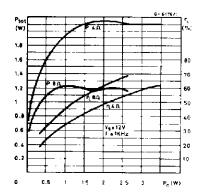


Figure 19. Total power dissipation and efficiency vs. output power

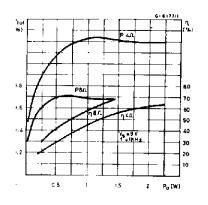
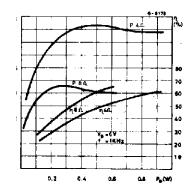


Figure 20. Total power dissipation and efficiency vs. output power



THERMAL SHUT-DOWN

The presence of a thermal limiting circuit offers the following advantages:

- An overload on the output (even if it is permanent), or an above limit ambient temperature can be easily tolerated since the T_j cannot be higher than 150°C.
- 2) The heatsink can have a smaller factor of safety compared with that of a conventional circuit. There is no possibility of device damage due to high junction temperature.

If for any reason, the junction temperature increase up to 150°C, the thermal shut-down simply reduces the power dissipation and the current consumption.

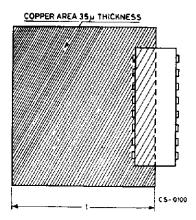
MOUNTING INSTRUCTION

The TDA 1904 is assembled in the Powerdip, in which 8 pins (from 9 to 16) are attached to the frame and remove the heat produced by the chip.

Figure 21 shows a PC board copper area used as a heatsink (I = 65 mm).

The thermal resistance junction-ambient is 35°C.

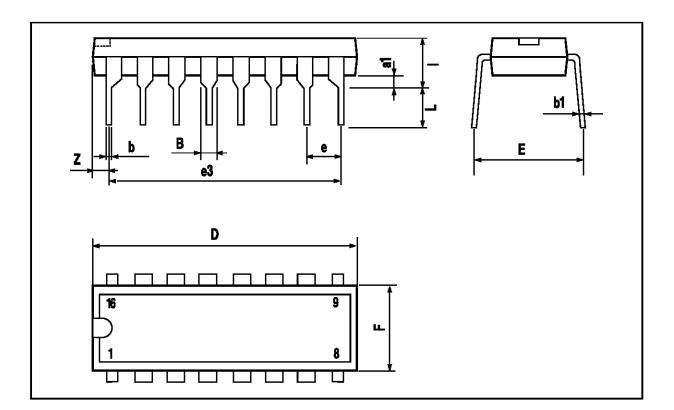
Figure 21. Example of heatsink using PC board copper (I = 65 mm)





DIM.		mm			inch	
Dilvi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
В	0.85		1.40	0.033		0.055
b		0.50			0.020	
b1	0.38		0.50	0.015		0.020
D			20.0			0.787
E		8.80			0.346	
е		2.54			0.100	
e3		17.78			0.700	
F			7.10			0.280
I			5.10			0.201
L		3.30			0.130	
Z			1.27			0.050

POWERDIP PACKAGE MECHANICAL DATA





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